

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application

1 1. (Original) An IC card comprising:

2 (a) a wiring substrate having an external connecting
3 terminal and wiring;

4 (b) a semiconductor chip disposed over the wiring
5 substrate and connected electrically to the external
6 connecting terminal through the wiring; and

7 (c) a case which covers the wiring substrate and the
8 semiconductor chip in such a manner that the external
9 connecting terminal of the wiring substrate is exposed,

10 wherein the case has a first end side near which the
11 external connecting terminal is disposed and a second end
12 side positioned on an opposite side to the first end side,
13 and

14 wherein a planar outline of the wiring substrate is
15 smaller than half of a planar outline of the case, and the
16 wiring substrate is disposed in an area of the case closer
17 to the first end side with respect to a middle position
18 between the first and the second end side.

1 2. (Original) An IC card according to claim 1,
2 wherein the semiconductor chip is disposed in an area of
3 the case closer to the first end side with respect to the
4 middle position between the first and the second end side.

1 3. (Original) An IC card according to claim 1,
2 wherein the case comprises a first case and a second case,
3 one of the first and the second case having a projecting
4 portion in an area other than the area where the wiring
5 substrate is disposed, the other case having a recess
6 portion in an area other than the area where the wiring
7 substrate is disposed, the projecting portion being fitted
8 in the recess portion so as to connect the first and the
9 second case with each other.

1 4. (Original) An IC card according to claim 3,
2 wherein a tip-side inner periphery portion of the recess
3 portion and a tip-side outer periphery portion of the
4 projecting portion are chamfered.

1 5. (Original) An IC card according to claim 3,
2 wherein the recess portion and the projecting portion have
3 an aligning function for self-alignmentwise aligning planar

4 positions of the first and the second case when both said
5 cases are superimposed one over the other.

1 6. (Original) An IC card according to claim 3,
2 wherein the projecting portion formed over the first or the
3 second case has a function for fixing the case formed with
4 the projecting portion to a carrier temporarily.

1 7. (Original) An IC card according to claim 1,
2 further comprising a movable switch,
3 wherein the case comprises a first case and a second
4 case, and in the first or the second case, a mechanism for
5 holding the movable switch is provided in an area other
6 than the area where the wiring substrate is disposed.

1 8. (Original) An IC card according to claim 1,
2 further comprising a movable switch, wherein the case
3 comprises a first case and a second case, and in the first
4 or the second case, a click mechanism for the movable
5 switch is provided in an area other than the area where the
6 wiring substrate is disposed.

1 9. (Original) An IC card according to claim 1,
2 further comprising a movable switch,
3 wherein the case comprises a first case and a second
4 case, and means for fixing the first and the second case to
5 a carrier temporarily are provided in areas of the first
6 and the second case other than the area where the wiring
7 substrate is disposed.

1 10. (Original) An IC card comprising:

2 (a) a wiring substrate having an external connecting
3 terminal and wiring;

4 (b) a semiconductor chip disposed over the wiring
5 substrate and connected electrically to the external
6 connecting terminal through the wiring; and

7 (c) a case which covers the wiring substrate and the
8 semiconductor chip in such a manner that the external
9 connecting terminal of the wiring substrate is exposed,

10 wherein a planar outline of the wiring substrate is
11 smaller than half of a planar outline of the case, and

12 wherein the case comprises:

13 a first end side near which the external connecting
14 terminal is disposed;

15 a second end side positioned on an opposite side to
16 the first end side;
17 a first area closer to the first end side with respect
18 to a middle position between the first and the second end
19 side, with the wiring substrate being disposed in the first
20 area; and
21 an insulating, second area positioned between the
22 first area and the second end side.

1 11. (Original) An IC card comprising:
2 (a) a wiring substrate having a plurality of external
3 connecting terminals and wiring;
4 (b) a semiconductor chip disposed over the wiring
5 substrate and connected electrically to the external
6 connecting terminals through the wiring; and
7 (c) a case having an opening into which some of the
8 plural external connecting terminals are exposed, the case
9 covering the wiring substrate and the semiconductor chip
10 and further covering some of the other external connecting
11 terminals.

1 12. (Original) An IC card according to claim 11,
2 wherein the case has a first end side near which the
3 external connecting terminals are disposed and a second end
4 side positioned on an opposite side to the first end side,
5 and

6 wherein a planar outline of the wiring substrate is
7 smaller than half of a planar outline of the case, and the
8 wiring substrate is disposed in an area of the case closer
9 to the first end side with respect to a middle position
10 between the first and the second end side.

13-20 (Cancelled)